INFORMATION ONLY NOTIFICATION

PCN # 20126102        Revision A

Title Of Change: Shipping, Logistics & Marking Changes

Publish Date: 08/23/12

Revision History of PCN:

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This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you have any questions concerning this change, please contact:

For North America:

EMAIL : PCNAmericasContact@list.ti.com
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PCN Requestor :
NAME : Kraintz, Jeff
Change Type: PACKING METHOD

PROPOSED 1st SHIP DATE
08/23/12

DESCRIPTION OF CHANGE AND PRODUCTS AFFECTED

Upon integration of National Semiconductor’s (NSC) manufacturing and order fulfillment systems with those of Texas Instruments (TI), changes to device top marking, shipping container labels, and shipping documents are required. The intent is to minimize the disruption to customers and only make changes that are necessary to integrate the systems.

TOP MARKING:

A - DATE CODE/TRACEABILITY: The device top marking will remain the same except for the date code format which will change from the current "UZYYWWT" format to the TI "YMLLLLS" format starting in October, 2012. See example below of the differences in the Date Code top mark for a device fabricated in the United Kingdom and assembled in Malaysia:

EXISTING NATIONAL SEMICONDUCTOR
"UZYYWWT" --&gt; KM1212AB
(U) Fab Site, K
(Z) Assembly Site, M
(YY) Calendar Year, 12
(WW) Calendar Week, 12
(TT) Die Trace Code, AB

NEW TEXAS INSTRUMENTS
"YMLLLLS" --&gt; 241234S
(Y) Year, 2
(M) Month, 4
(LLL) Lot Code, 1234
(S) Assembly Site S

B - MICRO SMD PIN 1: The Pin 1 top marking for all micro SMD products will convert from the symbol shape method, where the shape of the Pin 1 symbol (e.g. triangle, square) denotes the bump site, to the standard TI version of a circle. (No changes to Pin 1 orientation or location of Pin 1 top marking) - Beginning October, 2012

LABELING:

A - INTERMEDIATE BOXES: Intermediate box labels for Integrated Circuits, Sales Die, and Sales Wafer products will convert from the NSC standard (1D barcode) to TI’s standard (2D barcode). (see pg1 of attachment)
1) Beginning August 2012, Both NSC 1D and TI 2D labels will be applied on intermediate boxes to start preparing inventory for integration. To avoid any confusion, the TI 2D labels will be covered up by customer specific or blank labels and will not be visible to the customers.
2) Beginning October 2012, intermediate boxes on outgoing shipments to customers will be labeled with TI 2D labels. (Note: NSC 1D label will be covered by either the customer or blank label)

B - SALES DIE & SALES WAFERS: Labels applied to Sales Die or Sales Wafer products will convert from NSC 1D barcode or NSC text labels to TI 2D barcode or TI text labels (see pg3 of attachment).
Beginning October, 2012, Labels applied to
1) Sales Die packed in waffle trays, gel pack trays, and film frame wafer boats and the moisture barrier bags, in which they are sealed, will be labeled with TI text labels.
2) Sales Die packed in Surftape reels and the moisture barrier bags, in which they are sealed, will be labeled with TI standard 2D barcode labels.
3) Sales Wafers packed in wafer vials and the moisture barrier bags, in which they are sealed, will be labeled with TI text labels

NOTE: Post October 2012, either NSC 1D, NSC text or TI 2D, TI text labels will be present on the intermediate boxes, Sales Die or Sales Wafer products received by customers until all the NSC 1D labeled inventory is depleted.

Both NSC and TI labels are capable of providing lot traceability. Label formats/combinations for intermediate box, dry bag, and reel may vary over the course of the integration period. (see pg2 of attachment)

C - SHIPPING CARTONS: Shipping carton labels for Integrated Circuit, Sales Die, and Sales Wafer products will convert from NSC standard (1D barcode) to TI's standard (2D barcode) (see pg4 of attachment). - Beginning October, 2012, shipping cartons on outgoing shipments to customers will be labeled with TI 2D shipping carton labels
PACKING QUANTITY:

The Standard Pack Quantity (SPQ) for Sales Die packed in waffle trays will convert from the NSC standard to the TI standard. - Beginning September 2012, the SPQ for Sales Die packed in waffle trays will convert from the NSC standard 4 full trays in a sealed moisture barrier bag to TI’s standard 1 full tray in a sealed moisture barrier bag.

BRANDING:

Intermediate box company branding will convert to the TI standard (no company logo on box) - Beginning August, 2012

SHIPPING DOCUMENTS:

Delivery note and pro forma invoice will be converted to the TI standard – Beginning October, 2012

* The exact date for any of the above listed changes to first be seen by the customer will depend on inventory depletion status for the given product shipped.

REASON FOR CHANGE

As part of the integration process resulting from the acquisition of NSC by TI this past September, all former NSC manufacturing and order fulfillment systems will be integrated to those of TI.

ANTICIPATED IMPACT ON FORM, FIT, FUNCTION, QUALITY, OR RELIABILITY (POSITIVE / NEGATIVE)

No impact to form, fit, function, quality, or reliability. The design, manufacturing, and testing of all these products remain unchanged.

SAMPLE AVAILABILITY DATE SCHEDULE

Not applicable.

CHANGES TO PRODUCT IDENTIFICATION RESULTING FROM THIS PCN

All supporting documentation and package containers will be fully converted to TI processes. Device naming will remain the same.

RELIABILITY REFERENCE REPORTS

PART NUMBERS AFFECTED

ATTACHMENTS

NSC v TI Label comparison_PCN20126102b.pdf